

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	0	(trench with (second adj wafer) with ring) and (wafer adj package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 12:53	
2	BRS	L2	500	wafer adj package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 12:54	
3	BRS	L3	1388	wafer adj2 package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 13:08	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
4	BRS	L4	11	3 and (microcap or (micro adj size adj cap))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 13:01	
5	BRS	L5	105	3 and (second adj2 wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 13:01	
6	BRS	L6	1	5 and (first adj3 ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 13:02	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	L7	0	3 and (fill\$4 with trench with via with seal\$4)	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_T DB	2004/04/01 13:09	
8	BRS	L8	4	3 and (fill\$4 with trench with seal\$4)	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_T DB	2004/04/01 13:10	